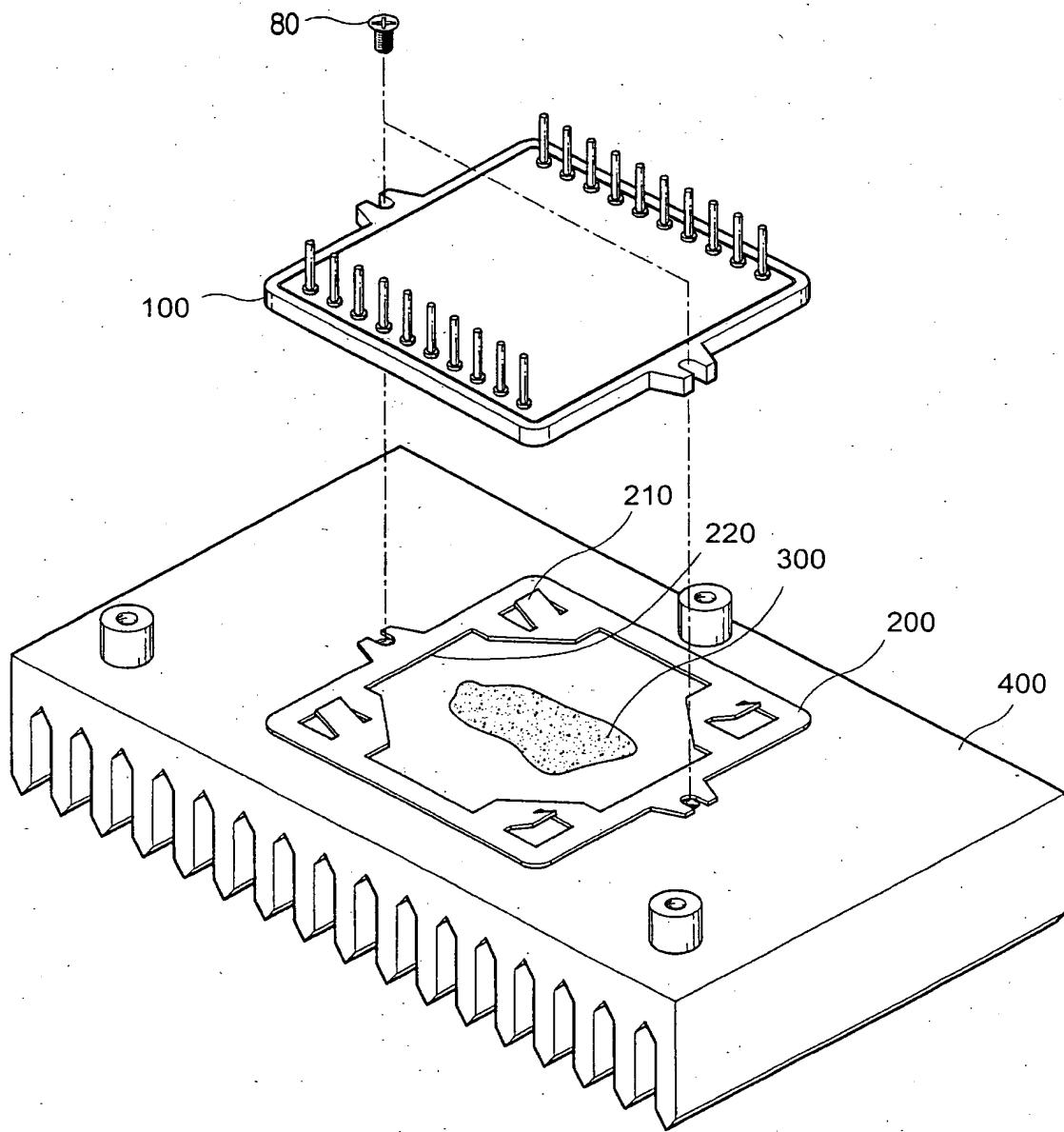
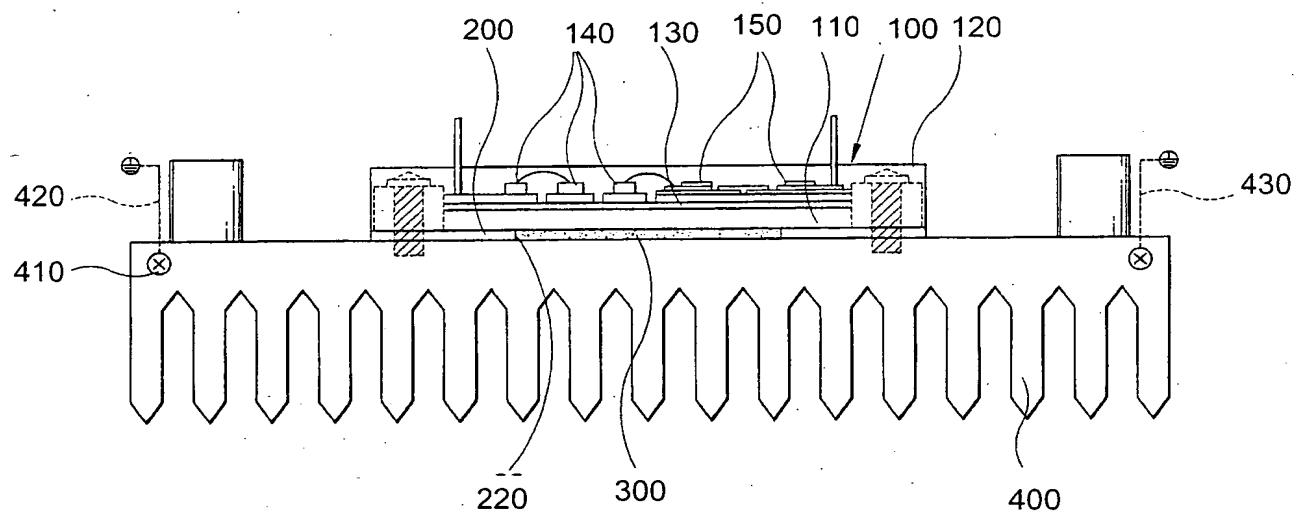


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FIG. 1

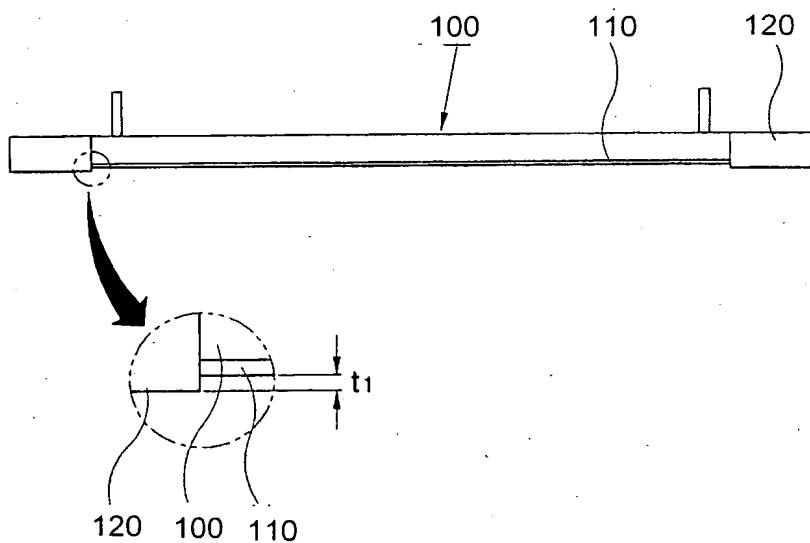


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FIG. 2



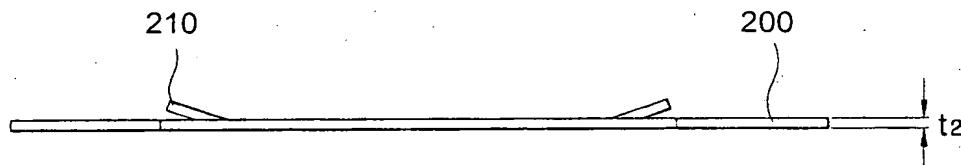
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FIG. 3



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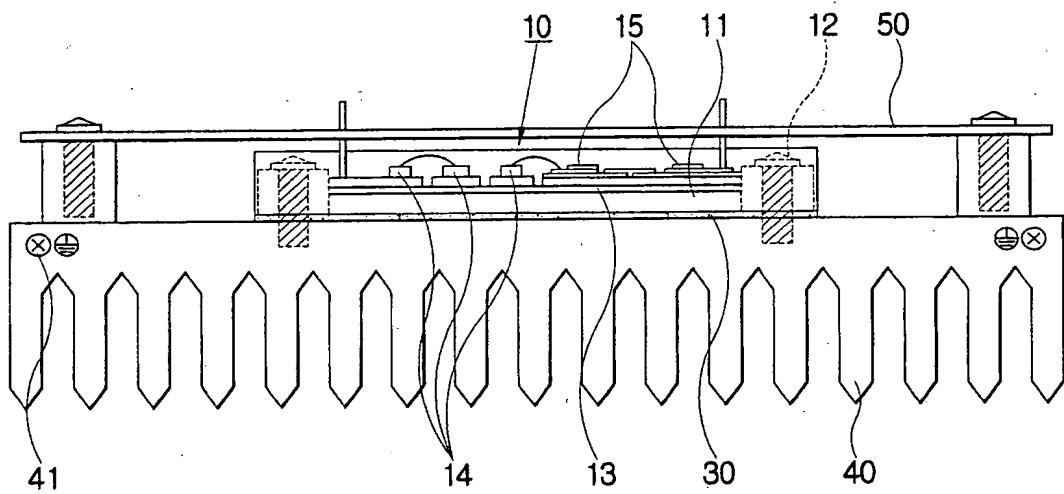
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FIG. 4



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FIG. 5
(PRIOR ART)



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FIG. 6

(PRIOR ART)

